



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-07-13
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	IPD MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	7ZDP*U36Q122	A	SHENZHEN B/E	2015-07-13
Amount	UoM	Unit type	ST ECOPACK Grade	
320	mg	Each	ECOPACK1	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
SIP	6.5, 6.1, 2.3	3	GULL WING	
Comment	Package: TO 252 DPAK, MD valid for CP:STPS15L45CB-TR.			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	false
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	true
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	7ZDP*U36Q122					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or Dies (choose)	Other inorganic materials	6.579	mg	supplier	die	Silicon (Si)	7440-21-3		6.303	mg	958048	19697
				supplier	metallization	Aluminium (Al)	7429-90-5		0.130	mg	19760	406
				supplier	Passivation	Silicon Oxide	7631-86-9		0.026	mg	3952	81
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	456	9
				supplier	back side metallization	Gold (Au)	7440-57-5		0.009	mg	1368	28
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.043	mg	6536	134
Leadframe	Copper & its alloys	166.150	mg	supplier	polymer die coating	Durimide	proprietary		0.065	mg	9880	203
				supplier	alloy	Copper (Cu)	7440-50-8		164.152	mg	987975	512975
				supplier	alloy	CopperPhosphorous (CuP)	12517-41-8		0.330	mg	1986	1031
				supplier	alloy	Cobalt (Co)	7440-48-4		0.462	mg	2781	1444
				supplier	metallization	Nickel (Ni)	7440-02-0		1.199	mg	7216	3747
Soft solder	Solder	6.083	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	5.809	mg	954956	18153
				supplier	solder	Silver (Ag)	7440-22-4		0.152	mg	24988	475
				supplier	solder	Tin (Sn)	7440-31-5		0.122	mg	20056	381
				supplier	wire	Aluminium (Al)	7429-90-5		0.739	mg	1000000	2309
Encapsulation	Other Organic Materials	139.404	mg	supplier	mold compound	Silica, vitreous	60676-86-0		112.360	mg	806003	351125
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		9.758	mg	69998	30494
				supplier	mold compound	Phenol resin	9003-35-4		5.576	mg	39999	17425
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		8.364	mg	59998	26138
				supplier	mold compound	Antimony Trioxide	1309-64-4		1.673	mg	12001	5228
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		0.976	mg	7001	3050
				supplier	mold compound	Carbon black	1333-86-4		0.697	mg	5000	2178
Connections coating	Solder	1.045	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		1.045	mg	1000000	3266